Gallium Nitride 50V 30W, RF Power Transistor

Description

The SME6003V is a 30-watt, unmatched GaN HEMT, designed for multiple applications with frequencies up to 6000MHz.

The performance is guaranteed for applications operating in the mentioned frequencies. There is no guarantee of performance when this part is used in applications designed outside of these frequencies.

SME6003V

•Typical performance (on Innogration fixture with device soldered)

VDD=50V, IDQ=70mA, CW,

| Frequency(MHz) | Gp (dB) | P _{3dB} (W) | Efficiency (%) |
|----------------|---------|----------------------|----------------|
| 2000 | 18 | 30 | 69 |

•Typical performance (on fixture with device soldered): VDD=50V IDQ=70mA, Pulse CW, Pulse Width=20 us, Duty cycle=10% ...

| Pulse CW | | | | | WCDMA Signal ⁽¹⁾ : P _{AVG} =36dBm | | | |
|--------------------|----------------------|-----------|----------------|------------------|---|------|----------------|----------------------|
| Frequency (MHz) | Gp@ P _{1dB} | P_{1dB} | η _D | P _{3dB} | η _D | Gp | η _D | ACPR _{5MHz} |
| (10112) | (dB) | (dBm) | (%) | (dBm) | (%) | (dB) | (%) | (dBc) |
| 3400 | 15.3 | 44.9 | 64.8 | 45.5 | 67.1 | 16.5 | 29.0 | -40.5 |
| 3500 | 15.9 | 44.5 | 61.1 | 45.6 | 66.6 | 17.0 | 27.9 | -39.1 |
| 3600 | 15.8 | 44.0 | 59.8 | 45.6 | 67.1 | 16.7 | 27.8 | -38.6 |

Note:(1) WCDMA signal: 3GPP test model 1; 1 to 64 DPCH; Channel Bandwidth=3.84MHz,PAR =10.5 dB at 0.01 % probability on CCDF.

Applications and Features

- Suitable for wireless communication infrastructure, wideband amplifier, EMC testing, ISM etc.
- High Efficiency and Linear Gain Operations
- Thermally Enhanced Industry Standard Package
- High Reliability Metallization Process

2. Reduce VGS down to VP, typically -5 V

1. Turn RF power off

4. Turn off VGS

3. Reduce VDS down to 0 V

- Excellent thermal Stability and Excellent Ruggedness
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

Important Note: Proper Biasing Sequence for GaN HEMT Transistors Turning the device ON Turning the device OFF

- 1. Set VGS to the pinch--off (VP) voltage, typically -5 V
- 2. Turn on VDS to nominal supply voltage (50V)
- 3. Increase VGS until IDS current is attained
- 4. Apply RF input power to desired level

Table 1. Maximum Ratings

| Rating | Symbol | Value | Unit |
|--------------------------------|------------------|-------------|------|
| DrainSource Voltage | V _{DSS} | +200 | Vdc |
| GateSource Voltage | V _{GS} | -8 to 0 | Vdc |
| Operating Voltage | V _{DD} | 0 to 55 | Vdc |
| Maximum forward gate current | lgf | 3.6 | mA |
| Storage Temperature Range | Tstg | -65 to +150 | С |
| Case Operating Temperature | Tc | -55 to +150 | С |
| Operating Junction Temperature | ΤJ | +225 | С |

Table 2. Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|--|--------|-------|------------|
| Thermal Resistance, Junction to Case | Rejc | 9.1 | <u>chu</u> |
| T_c = 85°C, T_J =200°C, DC Power Dissipation,FEA | KelC | 8.1 | C/W |

Table 3. Electrical Characteristics (T_C = 25°C unless otherwise noted)

DC Characteristics

| Characteristic | Conditions | Symbol | Min | Тур | Max | Unit |
|--------------------------------|---|----------------------|-----|------|-----|------|
| Drain-Source Breakdown Voltage | V _{GS} =-8V; I _{DS} =3.6mA | V _{DSS} | | 200 | | V |
| Gate Threshold Voltage | V _{DS} = 10V, I _D = 3.6mA | V _{GS} (th) | | -3.3 | | V |
| Gate Quiescent Voltage | V _{DS} =50V, I _{DS} =70mA, Measured in Functional Test | V _{GS(Q)} | | -3.0 | | v |

Functional Tests (In Innogration broadband Test Fixture, 50 ohm system) :V_{DD} = 50 Vdc, I_{DQ} = 70 mA, f = 2000 MHz, CW

| Characteristic | Symbol | Min | Тур | Max | Unit |
|---|--------|-----|------|-----|------|
| Power Gain | Gp | | 18 | | dB |
| Drain Efficiency@P3dBt | Eff | | 69 | | % |
| 3dB Compressed point | P3dB | | 30 | | W |
| Input Return Loss | IRL | | -10 | | dB |
| Mismatch stress at all phases(No device damage) | VSWR | | 10:1 | | Ψ |

Reference Circuit of Test Fixture Assembly Diagram

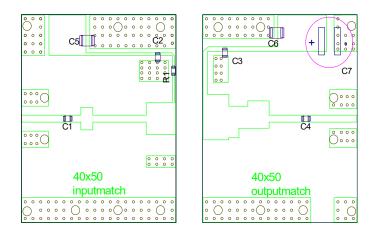


Figure 1. Test Circuit Component Layout (3400MHz~3600MHz)

Table 4. Test Circuit Component Designations and Values

| Designator | Value | Package | |
|----------------|------------------------------|----------------|--|
| C1, C2, C3, C4 | 6.8pF | 0805 | |
| C5, C6 | 10uF | 1210 | |
| R1 | 10 ^Ω | 0603 | |
| C7 | 100uF/63V | | |
| РСВ | 0.762mm [0.030"] t | hick, εr=3.48, | |
| | Rogers RO4350B, 1 oz. copper | | |

Figure 2. Pulse RF performance (3400MHz~3600MHz)

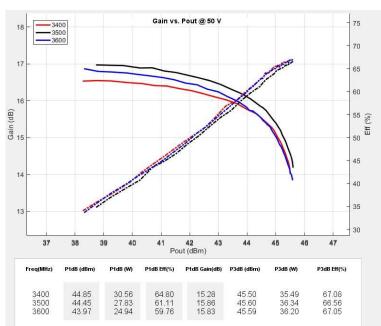


Figure 3. Network Analyzer result S11 and S21 (3400MHz~3600MHz)



Package Outline

Flanged ceramic package; 2 leads

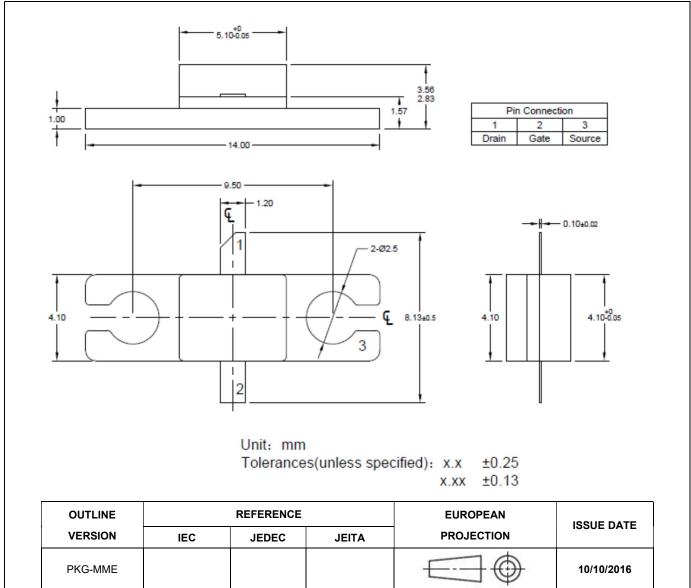


Figure 1. Package Outline PKG-MME

Revision history

Table 5. Document revision history

| Date | Revision | Datasheet Status |
|------------|----------|--|
| 2019/08/22 | V1.0 | Preliminary Datasheet Creation |
| 2020/1/2 | V1.1 | Modification on breakdown voltage rating |
| | | |

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